

PK605

Thermal Conductive Gel Pad

LiPOLY PK605 is a material designed for gap filling. The thermal conductivity is 6.0 W/m*K. The hardness is Shore OO/60 with high flexibility, high compressibility, high insulating, great self-adhesive, which can cover the tolerance of design making it very stable. It also offers customized shape molding service.

FEATURES

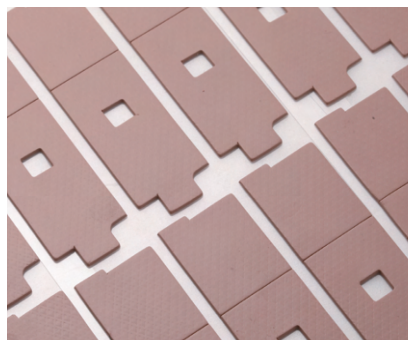
- / Thermal conductivity: 6.0 W/m*K
- / Naturally tacky for ease of manufacture
- / Low thermal impedance
- / Available in a range of thicknesses

TYPICAL APPLICATION

- / Notebook computers
- / Heat pipe assemblies
- / Memory modules
- / TV hardware
- / Automotive electronics
- / Mobile devices
- / High speed mass storage drives
- / Set-top box
- / IP CAM
- / 5G base station & infrastructure
- / EV electric vehicle

SPECIFICATIONS

- / Roll form / Sheet form
- / Die-cut parts



TYPICAL PROPERTIES

PROPERTY	PK605	TEST METHOD	UNIT
Color	Red	Visual	-
Surface tack 2-side/1-side	2	-	-
Thickness	Customized	ASTM D374	mm
Density	3.2	ASTM D792	g/cm ³
Hardness	60	ASTM D2240	Shore OO
Application temperature	-60~180	-	°C
ROHS & REACH	Compliant	-	-
COMPRESSION@1.0mm			
Deflection @10 psi	8	ASTM D5470 modify	%
Deflection @20 psi	12	ASTM D5470 modify	%
Deflection @30 psi	14	ASTM D5470 modify	%
Deflection @40 psi	17	ASTM D5470 modify	%
Deflection @50 psi	19	ASTM D5470 modify	%
ELECTRICAL			
Dielectric breakdown	12	ASTM D149	KV/mm
Surface resistivity	>10 ¹¹	ASTM D257	Ohm
Volume resistivity	>10 ¹⁰	ASTM D257	Ohm-m
THERMAL			
Thermal conductivity	6.0	ASTM D5470	W/m*K
Thermal impedance@10 psi	0.371	ASTM D5470	°C-in ² / W
Thermal impedance@20 psi	0.341	ASTM D5470	°C-in ² / W
Thermal impedance@30 psi	0.323	ASTM D5470	°C-in ² / W
Thermal impedance@40 psi	0.294	ASTM D5470	°C-in ² / W
Thermal impedance@50 psi	0.262	ASTM D5470	°C-in ² / W

Thermal Resistance vs. Pressure vs. Deflection

